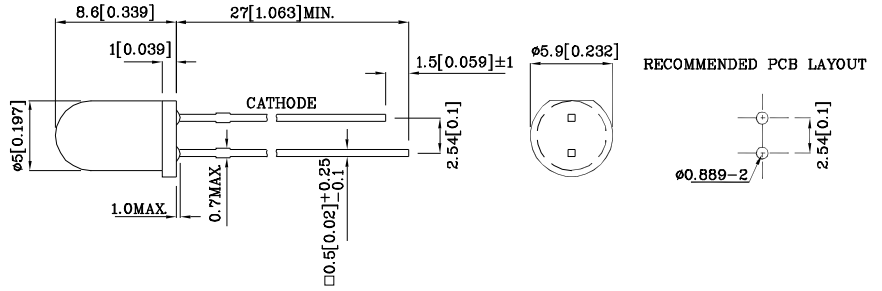


Features

- Radial / Through hole package
- Reliable & robust
- Low power consumption
- Available on tape and reel
- RoHS Compliant



Package Schematics



Notes:

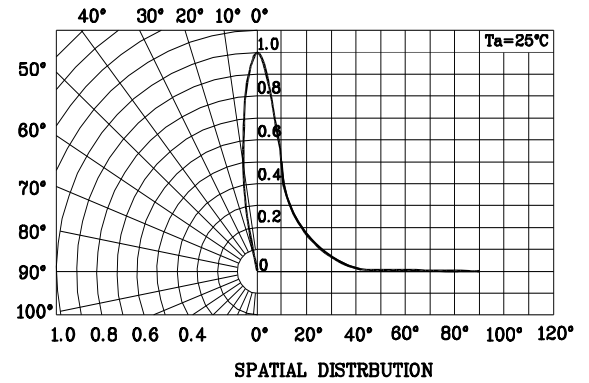
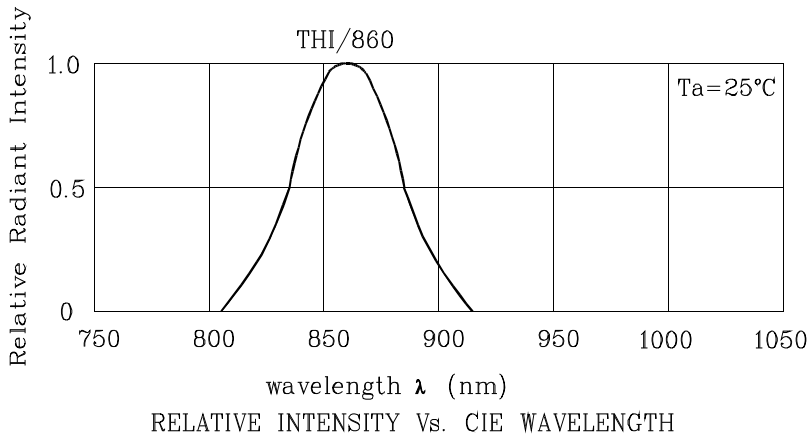
1. All dimensions are in millimeters (inches).
2. Tolerance is ±0.25(0.01") unless otherwise noted.
3. Specifications are subject to change without notice.

Absolute Maximum Ratings (T _A =25°C)		THI/860 (GaAlAs)	Unit
Reverse Voltage	V _R	5	V
Forward Current	I _F	50	mA
Forward Current (Peak) 1/10 Duty Cycle 0.1ms Pulse Width	iFS	1000	mA
Power Dissipation	P _D	80	mW
Operating Temperature	T _A	-40 ~ +85	°C
Storage Temperature	T _{stg}	-40 ~ +85	
Lead Solder Temperature [2mm Below Package Base]	260°C For 3 Seconds		
Lead Solder Temperature [5mm Below Package Base]	260°C For 5 Seconds		

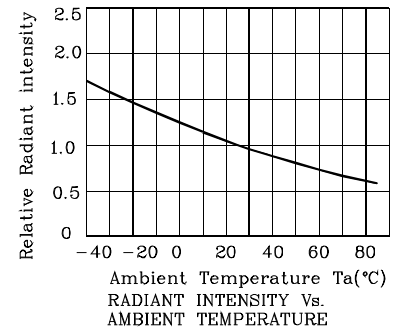
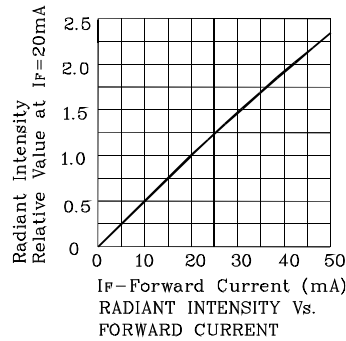
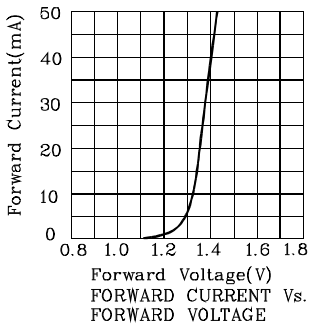
Operating Characteristics (T _A =25°C)		THI/860 (GaAlAs)	Unit
Forward Voltage (Typ.) (I _F =20mA)	V _F	1.35	V
Forward Voltage (Max.) (I _F =20mA)	V _F	1.6	V
Reverse Current (Max.) (V _R =5V)	I _R	10	uA
Wavelength of Peak Emission CIE127-2007* (Typ.) (I _F =20mA)	λP	860*	nm
Spectral Line Full Width At Half-Maximum (Typ.) (I _F =20mA)	Δλ	50	nm
Capacitance (Typ.) (V _F =0V, f=1MHz)	C	30	pF

Part Number	Emitting Material	Lens-color	Radiant Intensity CIE127-2007* (P _o =mW/sr) @20mA		Radiant Intensity CIE127-2007* (P _o =mW/sr) @50mA		Wavelength CIE127-2007* nm λP	Viewing Angle 2θ 1/2
			min.	typ.	min.	typ.		
XTHI12W860	GaAlAs	Water Clear	18*	39*	55*	98*	860*	20°

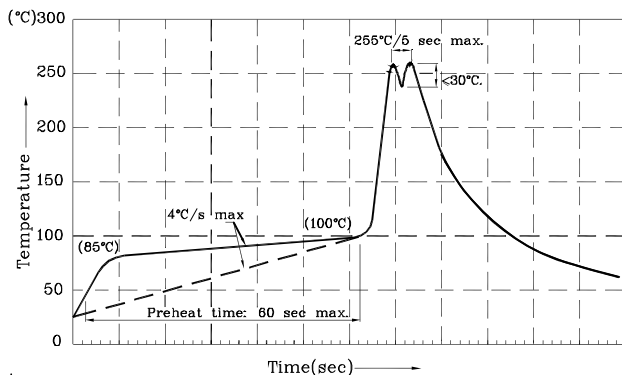
*Radiant intensity value and wavelength are in accordance with CIE127-2007 standards.



❖ THI/860



Wave Soldering Profile For Thru-Hole Products (Pb-Free Components)



Notes:

- 1.Recommend pre-heat temperature of 105°C or less (as measured with a thermocouple attached to the LED pins) prior to immersion in the solder wave with a maximum solder bath temperature of 280°C
- 2.Peak wave soldering temperature between 245°C ~ 255°C for 3 sec (5 sec max).
- 3.Do not apply stress to the epoxy resin while the temperature is above 85°C.
- 4.Fixtures should not incur stress on the component when mounting and during soldering process.
- 5.SAC 305 solder alloy is recommended.
- 6.No more than one wave soldering pass.

Remarks:

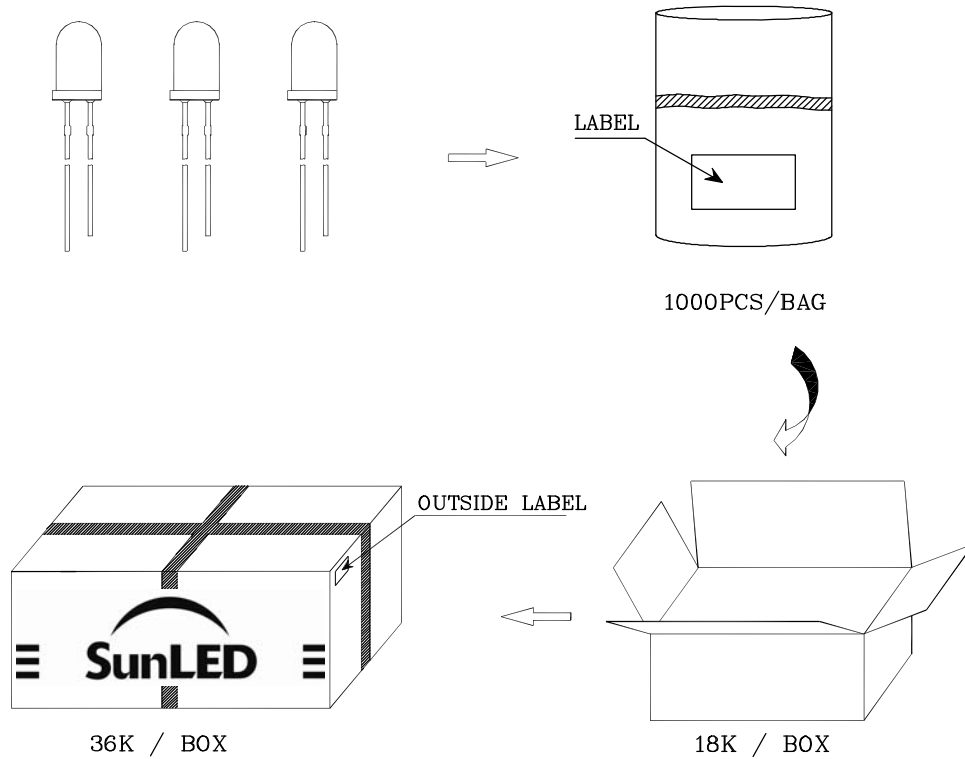
If special sorting is required (e.g. binning based on forward voltage, luminous intensity / luminous flux),



the typical accuracy of the sorting process is as follows:

1. Radiant Intensity / Luminous Flux: +/-15%
2. Forward Voltage: +/-0.1V

Note: Accuracy may depend on the sorting parameters.

PACKING & LABEL SPECIFICATIONS



		<table border="1"> <tr><td>Q.C.</td></tr> <tr><td>QC</td></tr> <tr><td>XX XX XXXX</td></tr> <tr><td>PASSED</td></tr> </table>	Q.C.	QC	XX XX XXXX	PASSED
Q.C.						
QC						
XX XX XXXX						
PASSED						
P/NO : XTxx12x						
QTY : 1000 pcs		CODE: XXX				
S/N : XX						
LOT NO:						
 XXXXXXXXXXXXXXXXXXXX						
RoHS Compliant						

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1. Data presented in this document reflect statistical figures and should be treated as technical reference only.
2. Contents within this document are subject to improvement and enhancement changes without notice.
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